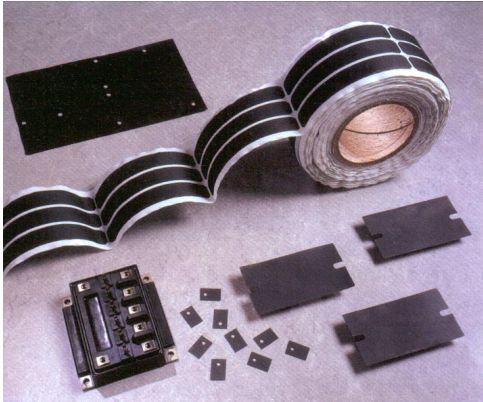


The Grease Replacement Material for Maximum Heat Transfer

Features and Benefits

- Thermal impedance
0.22°C-in²/W (@50 psi)
- Maximum heat transfer
- Aluminum foil coated both sides
- Designed to replace thermal grease



Q-Pad II is a composite of .0015" aluminum foil coated both sides with .0025" thermally/electrically conductive Sil-Pad rubber. It is designed for those applications where maximum heat transfer is needed and electrical isolation is not required. Q-Pad II is the ideal thermal interface material to replace messy thermal grease compounds.

Q-Pad II eliminates problems associated with grease such as contamination of reflow solder or cleaning operations. Q-Pad II can be used prior to these operations unlike grease. Q-Pad II also eliminates dust collection which can cause possible surface shorting or heat buildup.

Typical Properties of Q-Pad II						
Property	Imperial Value	Metric Value	Test Method			
Color	Black	Black	Visual			
Reinforcement Carrier	Aluminum	Aluminum	***			
Thickness, (inch) / (mm)	0.006	0.152	ASTM D374			
Hardness, (Shore A)	93	93	ASTM D2240			
Continuous Use Temp., (°F) / (°C)	-76 to 356	-60 to 180	***			
Electrical	Imperial Value	Metric Value	Test Method			
Dielectric Breakdown Voltage, (VAC)	Non-Insulating	Non-Insulating	ASTM D149			
Dielectric Constant, (1000 Hz)	NA	NA	ASTM D150			
Volume Resistivity, (Ohm-meter)	10 ²	10 ²	ASTM D257			
Flame Rating	94 V-O	94 V-O	U.L.			
Thermal	Imperial Value	Metric Value	Test Method			
Thermal Conductivity, (W/m-K)	2.5	2.5	ASTM D5470			
Thermal Impedance vs. Pressure						
	Pressure (psi)	10	25	50	100	200
TO-220 Thermal Performance, (°C/W)		2.44	1.73	1.23	1.05	0.92
Thermal Impedance, (°C-in ² /W) (I)		0.52	0.30	0.22	0.15	0.12

1). The ASTM D5470 (Bergquist Modified) test fixture was used. The recorded value includes interfacial thermal resistance. These values are given to the customer for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Typical Applications Include

- Between a transistor and a heat sink
- Between two large surfaces such as an L-bracket and the chassis of an assembly
- Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

Configurations

Available:

- Sheet form
- Die-Cut parts
- Roll form
- With or without pressure sensitive adhesive

We produce thousands of specials. Tooling charges vary depending on tolerances and complexity of the part.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

U.L. File Number E59150

Product Data Sheet / PDS-0602-001-01; Rev 01